501915906 05/10/2012

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Su-Tsai Lu	04/18/2012
Jing-Ye Juang	04/18/2012

RECEIVING PARTY DATA

Name:	Industrial Technology Research Institute
Street Address:	No. 195, Sec. 4, Chung Hsing Rd., Chutung,
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	31040

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13467054

CORRESPONDENCE DATA

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via US Mail.

Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE

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Address Line 4: TAIPEI, TAIWAN 100

ATTORNEY DOCKET NUMBER: 40907-US-PA

NAME OF SUBMITTER: Belinda Lee

Total Attachments: 2

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PATENT REEL: 028184 FRAME: 0875 CH \$40.00

P51000157US 40907-US-PA

ASSIGNMENT

WHEREAS

1. Su-Tsai Lu

2. Jing-Ye Juang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CHIP STACK STRUCTURE AND METHOD FOR FABRICATING THE SAME

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute

of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P51000157US 40907-US-PA

ASSIGNMENT CONTINUED

indicated.	/HEREOF, Assignor ha	s/have signed his/he	r/their name(s) on the date(s	;)
Signature:	Su-Tsai	Date: _	2012, 04. 18	
Sole or First Joint	Inventor: Su-Tsai Lu			
Signature:	Jing-Ye, Jua	Date: _	>612.04, 18	
Second Joint Inve	ntor (ir any): Jing-Ye Jເ	lang	•	

RECORDED: 05/10/2012